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DISCLOSURE TEXT:

A sheet of thin film resistor material is used to provide the power resistors in a packaging technology using a laminate substrate of aluminum and polyimide. This technique allows automated manufacture of resistive components with low temperature processed substrate materials. The resistor material is sandwiched between a copper conductor sheet and a laminate substrate and etched to the proper resistor value and conductor pattern. By making the laminate substrate polyimide, or another suitable dielectric, and then attaching it to an aluminum base, power supply or other high power circuitry and all power and other resistors are fabricated at one time. The power dissipation capability is limited only by the ability of the aluminum base to dissipate heat. The aluminum base may be an aluminum plate or powdered metal.

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